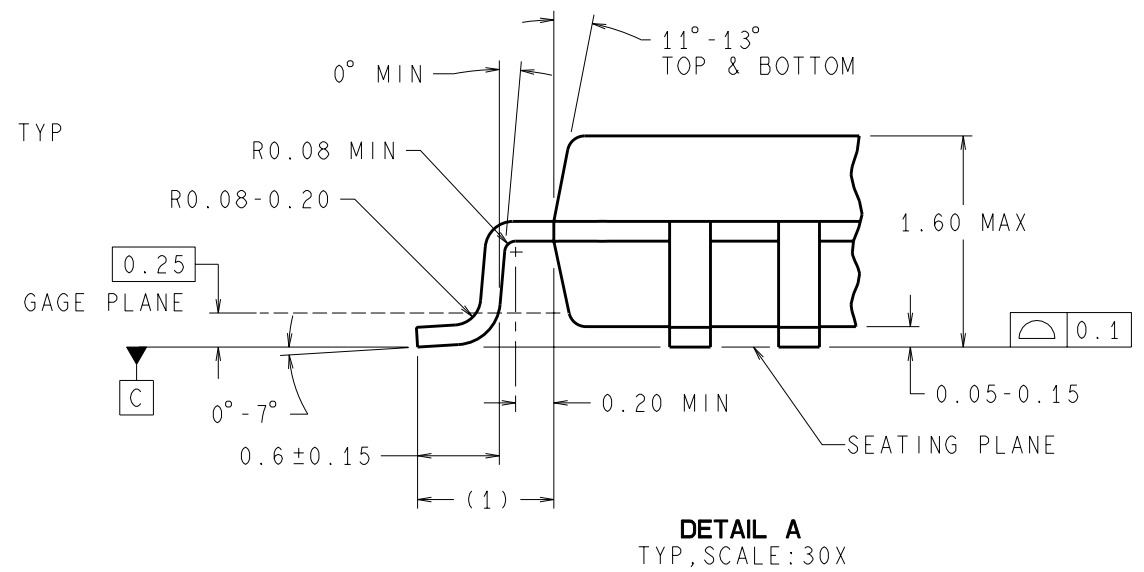
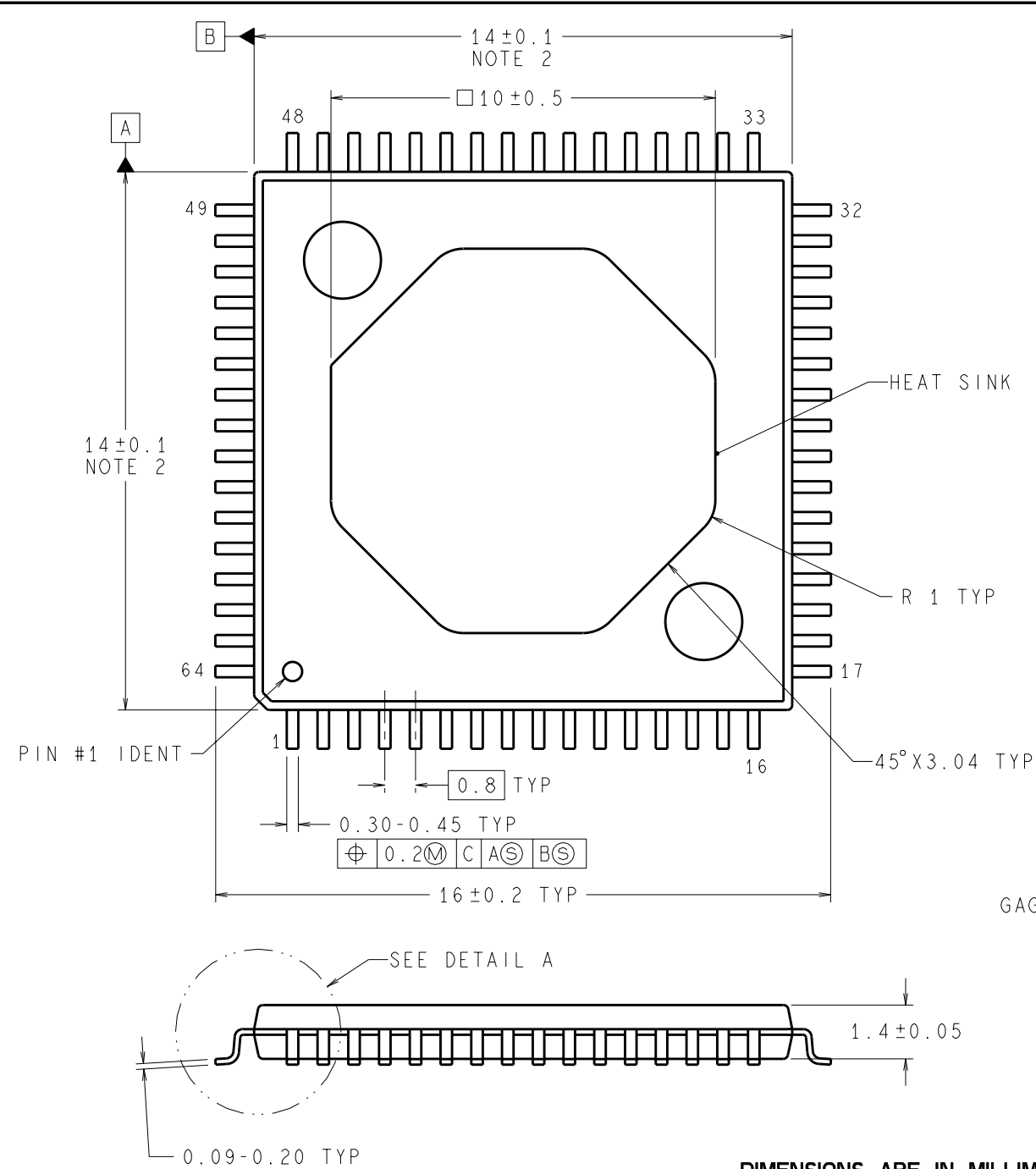


| REVISIONS |  |        |            |          |
|-----------|--|--------|------------|----------|
| LTR       | DESCRIPTION  | E.C.N. | DATE       | BY/APP'D |
| A         | RELEASE TO DOCUMENT CONTROL                                  | 11588  | 10/09/1996 | TL/SM    |
| B         | TITLE: LOFP WAS TOFP; UPDATE NOTE 3; ADD GEOMETRIC TOLERANCE | 12317  | 11/10/1999 | TL/RW    |



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:  
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)  
THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.  
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- CAVITY OPTIONS:  
a. HEAT SINK FACING UP FOR CAVITY DOWN (SHOWN).  
b. HEAT SINK FACING DOWN FOR CAVITY UP.
- REFERENCE JEDEC REGISTRATION MS-026, VARIATION BEB,  
DATED FEBRUARY 1999.

|                             |            |   |                |     |
|-----------------------------|------------|---|----------------|-----|
| APPROVALS                   | DATE       | National Semiconductor  |                |     |
| DRAWN<br>T. LEQUANG         | 10/09/1996 | 2900 Semiconductor Dr., Santa Clara, CA 95052-8090              |                |     |
| DFTG. CHK.<br>MARTA SUCHY   | 11/10/1999 | LOFP, JEDEC METRIC,<br>14 X 14 X 1.4mm,<br>64 LEAD, EXPOSED H/S |                |     |
| ENGR. CHK.<br>RANDY WALBERG | 11/10/1999 |   |                |     |
| PROJECTION                  | SCALE      | SIZE  | DRAWING NUMBER | REV |
|                             | N/A        | C   | (SC)MKT-VJK64A | B   |
| FORMERLY: N/A               |            | SHEET 1 of 1  |                |     |